

Title (en)
ADDITION CURABLE SILICONE ADHESIVE COMPOSITIONS

Title (de)
ADDITIONSHÄRTBARE SILIKON-KLEBSTOFF-ZUSAMMENSETZUNGEN

Title (fr)
COMPOSITIONS ADHÉSIVES DE SILICONE DURCISSABLES PAR ADDITION

Publication
EP 3914638 A1 20211201 (EN)

Application
EP 19706813 A 20190123

Priority
US 2019014702 W 20190123

Abstract (en)
[origin: WO2020153947A1] A curable silicone adhesive composition comprising adhesion promoter is shown and described herein. The adhesion promoter is a silicon hydride material containing an aromatic based skeleton with another adhesion promoter to provide a silicone material that is curable at relatively low temperatures and shorter time and provides good adhesion to plastics and metal.

IPC 8 full level
C08J 5/12 (2006.01); **C08G 77/12** (2006.01); **C08G 77/14** (2006.01); **C08G 77/20** (2006.01); **C08K 3/36** (2006.01); **C08K 5/5415** (2006.01);
C08K 5/5419 (2006.01); **C08L 83/06** (2006.01); **C09J 183/04** (2006.01)

CPC (source: EP KR US)
C08G 77/12 (2013.01 - EP KR); **C08G 77/14** (2013.01 - EP); **C08G 77/20** (2013.01 - EP KR); **C08K 3/36** (2013.01 - EP);
C08K 5/5415 (2013.01 - EP KR); **C08K 5/5419** (2013.01 - EP KR); **C08L 83/04** (2013.01 - KR); **C08L 83/06** (2013.01 - EP US);
C09J 7/25 (2018.01 - US); **C09J 7/255** (2018.01 - US); **C09J 7/28** (2018.01 - US); **C09J 7/30** (2018.01 - EP KR); **C09J 7/35** (2018.01 - US);
C09J 183/04 (2013.01 - EP KR); **C09J 183/06** (2013.01 - US); **C08L 2205/035** (2013.01 - US); **C09J 2301/304** (2020.08 - US);
C09J 2301/408 (2020.08 - EP KR); **C09J 2400/163** (2013.01 - US); **C09J 2467/006** (2013.01 - US); **C09J 2481/006** (2013.01 - US);
C09J 2483/00 (2013.01 - EP KR US)

C-Set (source: EP)
1. **C09J 183/04 + C08L 83/00**
2. **C08K 3/36 + C08L 83/04**
3. **C08K 5/5415 + C08L 83/04**
4. **C08K 5/5419 + C08L 83/04**
5. **C08L 83/06 + C08L 83/00**

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
WO 2020153947 A1 20200730; CN 113518794 A 20211019; CN 113518794 B 20231222; EP 3914638 A1 20211201;
JP 2022522100 A 20220414; JP 7407825 B2 20240104; KR 20210118866 A 20211001; TW 202033722 A 20200916; US 11952516 B2 20240409;
US 2022119690 A1 20220421

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US 2019014702 W 20190123; CN 201980093362 A 20190123; EP 19706813 A 20190123; JP 2021543201 A 20190123;
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